L	L#	Hits	Search Text	DBs
1	L1	525	361/720.ccls.	US- PGPUB ; USPAT
2	L2 .	0	1 and ((core with ((dissipat\$3 thermal\$2) adj layer\$1)) with (coefficient\$1 expansion cte tce tec))	US- PGPUB ; USPAT
3	L3	0	1 and (core with ((dissipat\$3 thermal\$2) adj layer\$1)) with (coefficient\$1 expansion cte tce tec)	US- PGPUB ; USPAT
4	L4	8	1 and (core with (coefficient\$1 expansion cte tce tec))	US- PGPUB ; USPAT
5	L5	105	1 and ((dissipation cooling) and (coefficient\$1 expansion cte tce tec))	US- PGPUB ; USPAT
6	L6	100	5 not 4	US- PGPUB ; USPAT
7	L7	1161	361/719.ccls.	US- PGPUB ; USPAT
8	L8	0	7 and (core with ((dissipat\$3 thermal\$2) adj layer\$1)) with (coefficient\$1 expansion cte tce tec)	US- PGPUB ; USPAT

	L#	Hits	Search Text	DBs
9	L9	7	7 and (core with (coefficient\$1 expansion cte tce tec))	US- PGPUB ; USPAT
10	L10	431	(361/780,794.ccls.)	US- PGPUB ; USPAT
11	L11	72	10 and (multi\$1chip mcm "plurality of (chip\$1 semiconductor\$1 die\$1)")	US- PGPUB ; USPAT
12	L12	1684	257/723.ccls.	US- PGPUB ; USPAT
13	L13	0	12 and (("interconnected with each other") ("interconnected with one another"))	US- PGPUB ; USPAT
14	L14	487	12 and (multi\$1layer\$2 multi\$1level)	US- PGPUB ; USPAT
15	L15	219	14 and (multi\$1chip mcm "plurality of (chip\$1 semiconductor\$1 die)")	US- PGPUB ; USPAT
16	L16	0	wo-02061827-\$.did.	DERWE NT